Claims

1. A method of making a system-in-package device, the method comprising

including in the system-in package device at least one first species die with predetermined dimensions, at least one second species die with predetermined dimensions, and at least one further component of the system-in-device;

selecting at least one of the first and second species dies for redimensioning;

adding material to at least one side of the selected die(s) such that the added material and the selected die(s) form a redimensioned die structure;

forming a connecting layer on the redimensioned die structure;

dimensioning the redimensioned die structure to allow mounting of the non-selected die and the at least one further component into contact with the redimensioned die structure via the connecting layer.

2. The method according to claim 1, **wherein** the method further comprises:
- manufacturing on to a native first wafer a first plurality of first species dies with a first allotment of the first species dies on said native first wafer, the predetermined dimensions of the one first species die being determined by the first allotment;
- manufacturing on to a native second wafer a second plurality of second species dies with a second allotment of the second species dies on said native second wafer, the predetermined dimensions of the one second species die being determined by the second allotment.

3. The method according to claim 1 or 2, **wherein** the at least one further component of the system-in-device is a connection member for input and output operations of the system-in-package device.

4. The method according to claim 1, 2 or 3, **wherein** the method comprises including two or more dies into the redimensioned die structure.

5. The method according to claim 1, 2 or 3, **wherein** the method comprises mounting two or more dies into contact with the redimensioned die structure via the connecting layer.